

CLAIM AMENDMENTS

Claims 1-15 (Cancelled).

16. (New) A semiconductor device structure comprising:
a substrate;

a first packaged integrated circuit including a package and having a plurality of terminals extending outwardly from a periphery of the package, the first packaged integrated circuit being mounted on the substrate; and

a second packaged integrated circuit including a package and having a plurality of terminals extending outwardly from a periphery of the package, the second packaged integrated circuit being mounted on the substrate, wherein

at least some of the terminals of the first packaged integrated circuit are connected to corresponding terminals of the second integrated circuit, and

the terminals of the first and second packaged integrated circuits that are connected to each other are arranged facing each other on the substrate whereby the first and second packaged integrated circuits are compactly mounted on the substrate.

17. (New) The semiconductor device structure according to claim 16, wherein the packages of the first and second packaged integrated circuits have respective sides from which the respective terminals that are connected to each other project and the respective sides of the first and second packaged integrated circuits face each other.

18. (New) The semiconductor device structure according to claim 16, wherein the packages of the first and second packaged integrated circuits each have a plurality of sides from which the respective terminals project and the terminals of the first and second packaged integrated circuits that are connected to each other are all located on first and second sides of the first packaged integrated circuit and on a first side of the second packaged integrated circuit, the first and second sides of the first packaged integrated circuit facing the first side of the second packaged integrated circuit.

19. (New) The semiconductor device structure according to claim 18, wherein the packages of the first and second integrated circuits are rectangular and a corner at the first and second sides of the package of the first packaged integrated circuit faces the first side of the second packaged integrated circuit.

20. (New) The semiconductor device structure according to claim 16, wherein the terminals of the first packaged integrated circuits that are connected to terminals of the second packaged integrated circuit are arranged in a group, in series, the terminals of the second packaged integrated circuit that are connected to terminals of the first packaged integrated circuit are arranged in a group, in series, and the terminals of the first packaged integrated circuit are arranged in the same order as the terminals of the second packaged integrated circuit.

21. (New) The semiconductor device structure according to claim 16, wherein the first packaged integrated circuit comprises:
a power source input terminal for receiving a power source voltage from the second packaged integrated circuit,
an oscillating unit connected to the power source input terminal and generating an AC signal having a frequency, and
a multiplying unit which changes the frequency of the signal which the oscillating unit generates to produce a multiplied signal, and
an output terminal which outputs the multiplied signal; and
the second packaged integrated circuit comprises:
a power source output terminal which supplies the power source voltage to the power source input terminal of the first packaged integrated circuit, and
a signal input terminal for receiving the signal from the output terminal.

22. (New) The semiconductor device structure according to claim 21, wherein the first packaged integrated circuit further comprises:
a power source voltage supplying unit which supplies power to the oscillating unit;
and
a power source switching unit which supplies power from the power source voltage supplying unit to the oscillating unit and to the multiplying unit when the power source voltage supplying unit supplies power, and which supplies power from the power source input terminal to the oscillating unit and the multiplying unit when the power source voltage supplying unit does not supply power.

23. (New) The semiconductor device structure according to claim 16, wherein the first and the second packaged integrated circuits are mounted on the same side of the substrate.

24. (New) The semiconductor device structure according to claim 16, wherein the first and the second packaged integrated circuits are mounted on the opposite sides of the substrate and connections between connected terminals of the first and second packaged integrated circuits pass through respective through-holes in the substrate.

25. (New) The semiconductor device structure according to claim 16, wherein the packages of each of the first and second packaged integrated circuits have respective facing sides, the facing sides of the first and second packaged integrated circuits face each other, and the terminals of the first packaged integrated circuit project from the facing side of the first packaged integrated circuit and from two sides of the first packaged integrated circuit that are respectively adjacent to the facing side of the first packaged integrated circuit.

26. (New) A semiconductor device structure comprising:
a substrate;

a first packaged integrated circuit including a rectangular package having a pair of longer sides and a pair of shorter sides and having a plurality of terminals extending outwardly from the longer sides of the package, the first packaged integrated circuit being mounted on the substrate; and

a second packaged integrated circuit including a rectangular package having a pair of longer sides and a pair of shorter sides and having a plurality of terminals extending outwardly from the longer sides of the package, the second packaged integrated circuit being mounted on the substrate, wherein

at least some of the terminals of the first packaged integrated circuit, as a first group of terminals, are connected to corresponding terminals of a second group of terminals of the second integrated circuit,

shorter sides of each of the first and second packaged integrated circuit face each other, and

the first group of terminals and the second group of terminals are arranged in series, the terminals of the first and second groups are arranged the same order on the packages of the first and second packaged integrated circuits, and the terminals of the first

and second groups closest to the shorter sides of the packages of the first and second packaged integrated circuits that face each other are connected to each other

27. (New) The semiconductor device structure according to claim 26, wherein the first packaged integrated circuit comprises:

a power source input terminal for receiving a power source voltage from the second packaged integrated circuit,

an oscillating unit connected to the power source input terminal and generating an AC signal having a frequency, and

a multiplying unit which changes the frequency of the signal which the oscillating unit generates to produce a multiplied signal, and

an output terminal which outputs the multiplied signal; and

the second packaged integrated circuit comprises:

a power source output terminal which supplies the power source voltage to the power source input terminal of the first packaged integrated circuit, and

a signal input terminal for receiving the signal from the output terminal.

28. (New) The semiconductor device structure according to claim 27, wherein the first packaged integrated circuit further comprises:

a power source voltage supplying unit which supplies power to the oscillating unit; and

a power source switching unit which supplies power from the power source voltage supplying unit to the oscillating unit and to the multiplying unit when the power source voltage supplying unit supplies power, and which supplies power from the power source input terminal to the oscillating unit and the multiplying unit when the power source voltage supplying unit does not supply power.